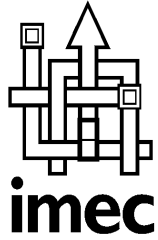


# **Chemical Analysis on Focused Ion Beam Cross-Sections by Scanning Auger Microscopy**

**H. Bender**  
IMEC, Leuven, Belgium

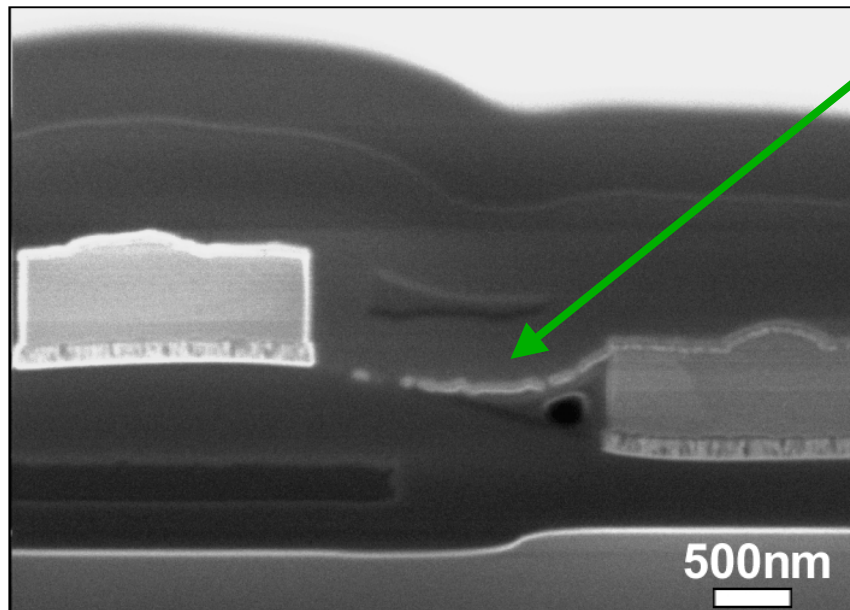
EFUG2001  
1 October 2001, Arcachon, France



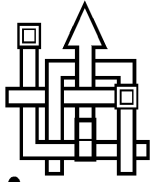
# Outline

- **Introduction**
- **FIB and AES configurations**
- **Application : Cu dual damascene chain**
- **Conclusions**

- **what is this ?**



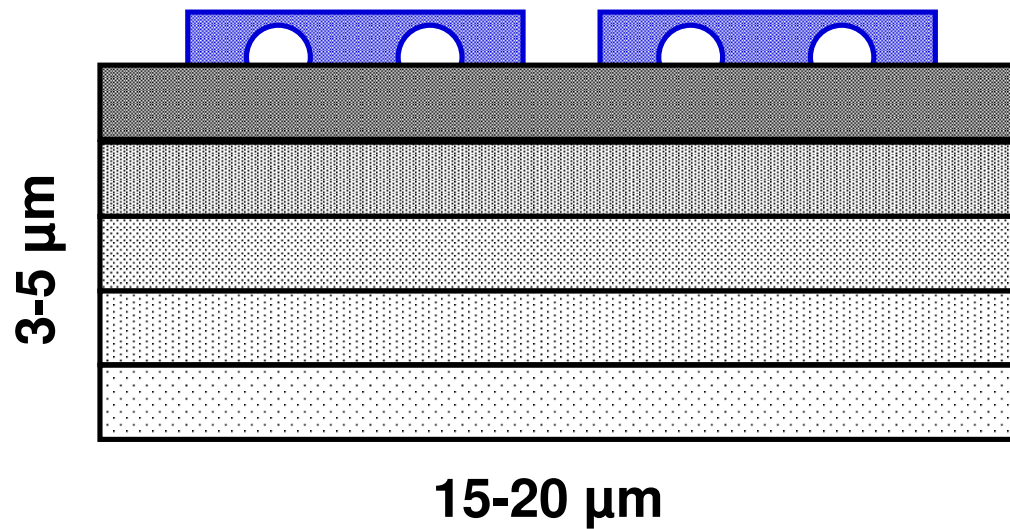
- **analysis :**
  - **FIB contrast**
  - **SIMS (in-situ)**
  - **EDS (in-situ or ex-situ)**
  - **AES (ex-situ) :**
    - **best lateral resolution**
    - **sensitive to all elements**
    - **surface sensitive**



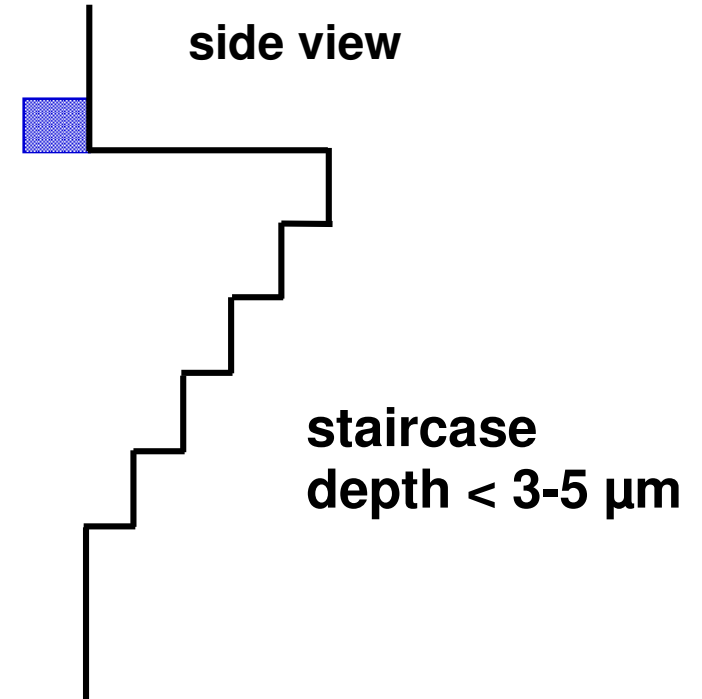
imec

# Typical crater sputtering

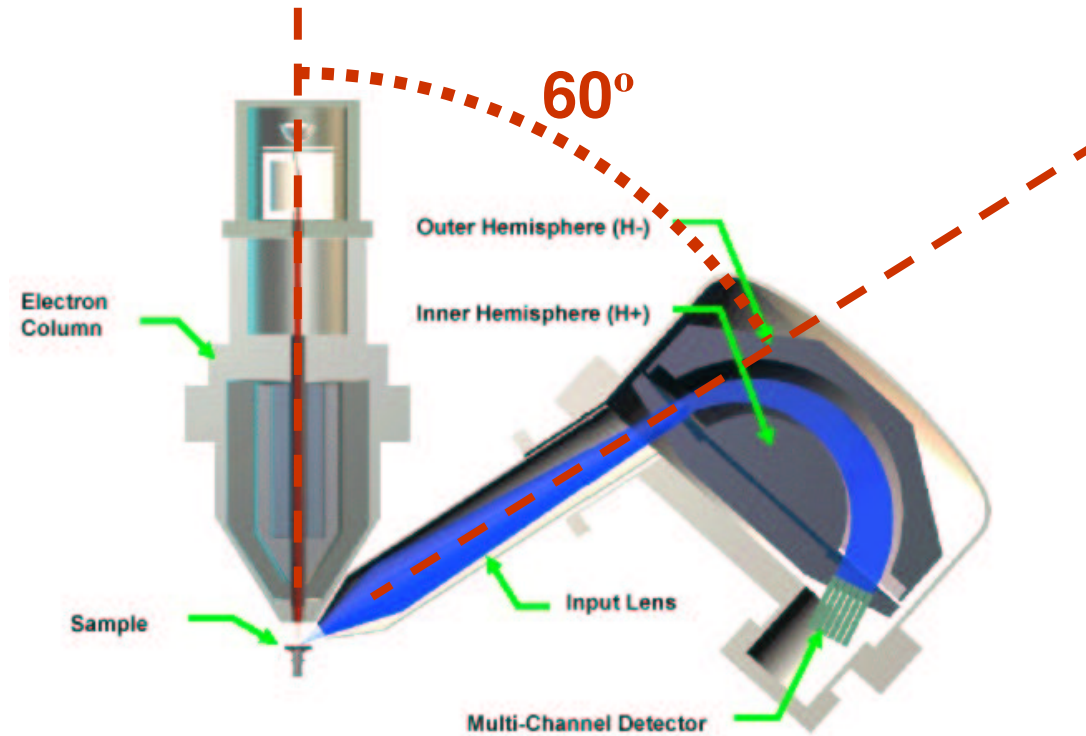
top view

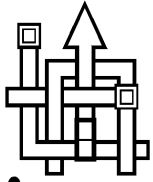


side view



# AES configuration

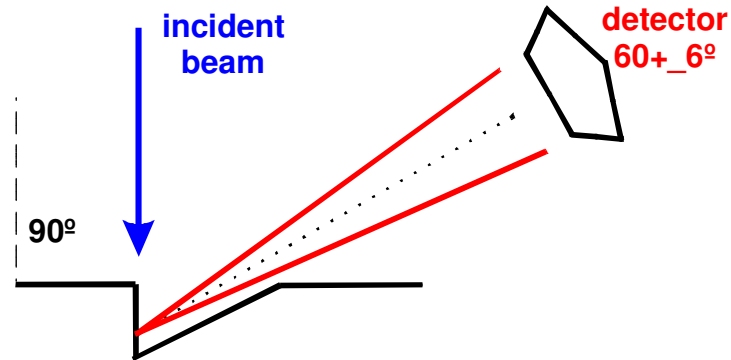




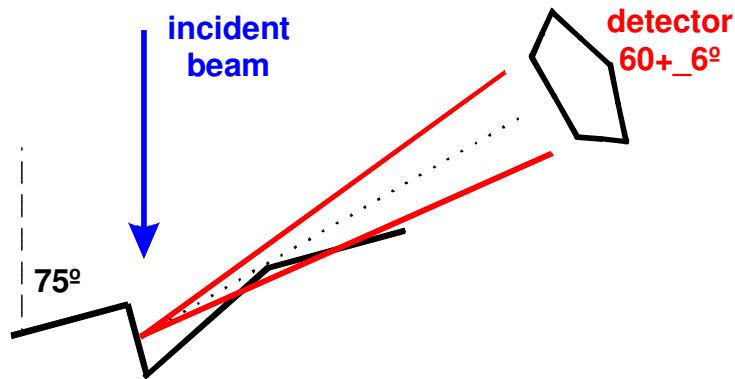
imec

# Configuration FIB crater - analyser

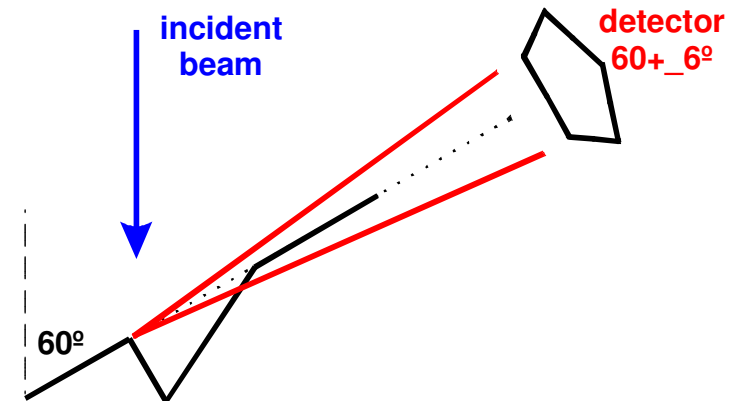
no image :



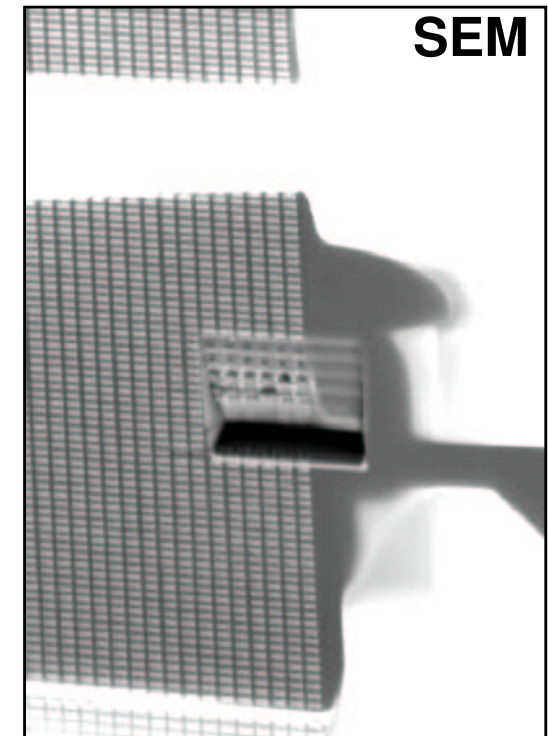
partial detection :



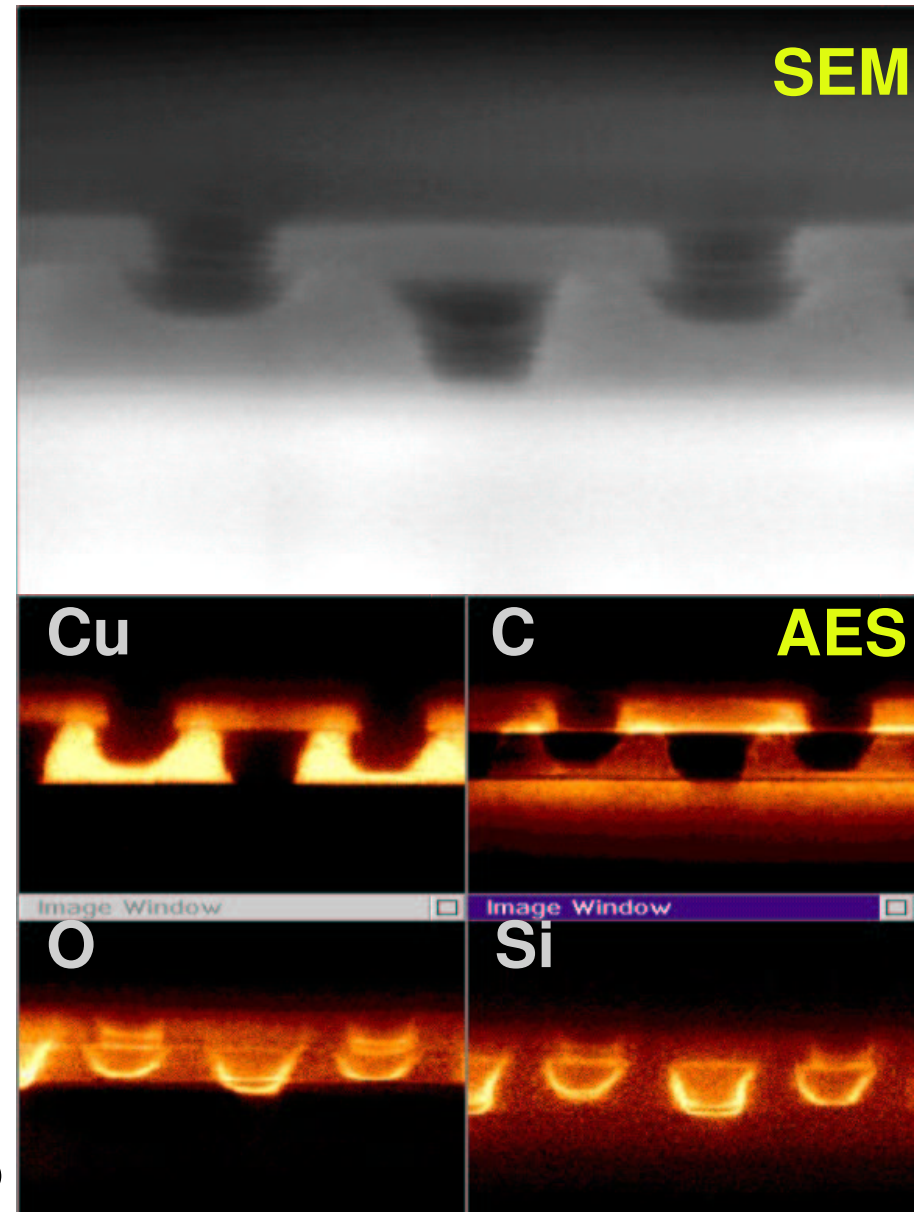
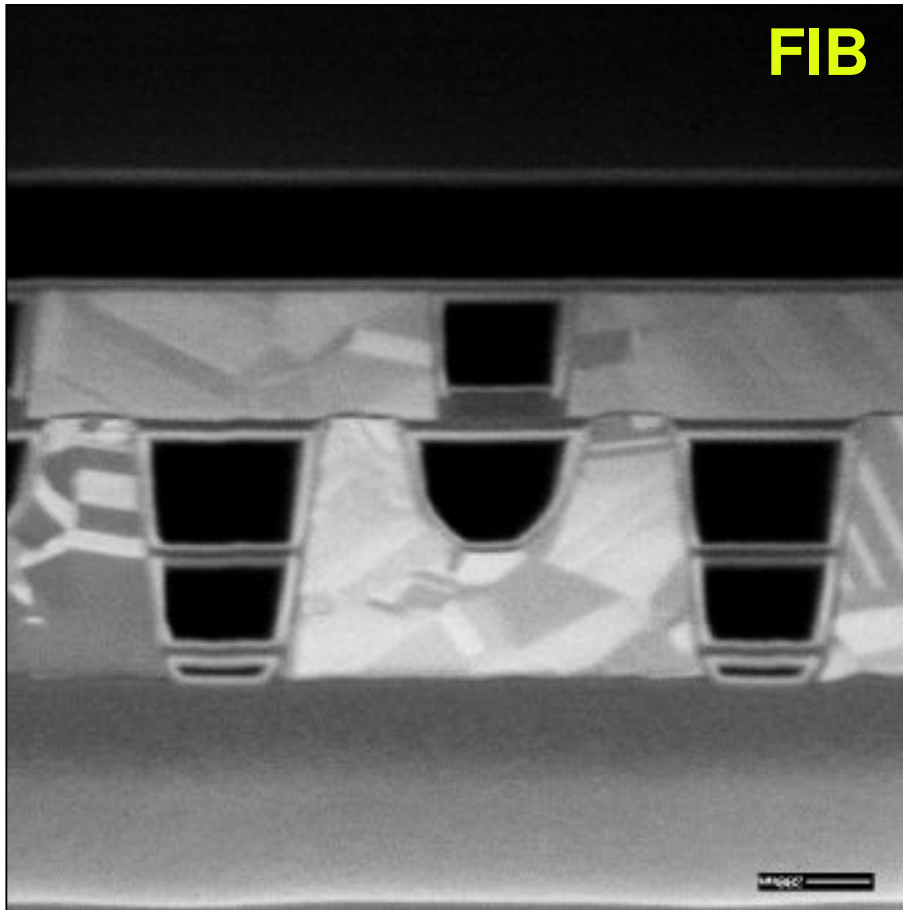
no detection:



*2:1 aspect ratio crater*



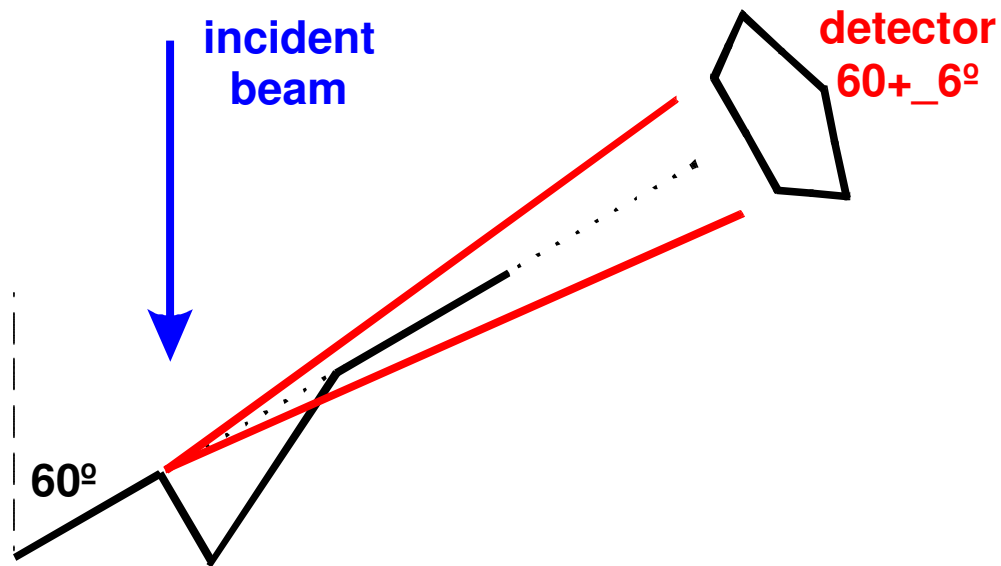
# FIB - AES Cu chains



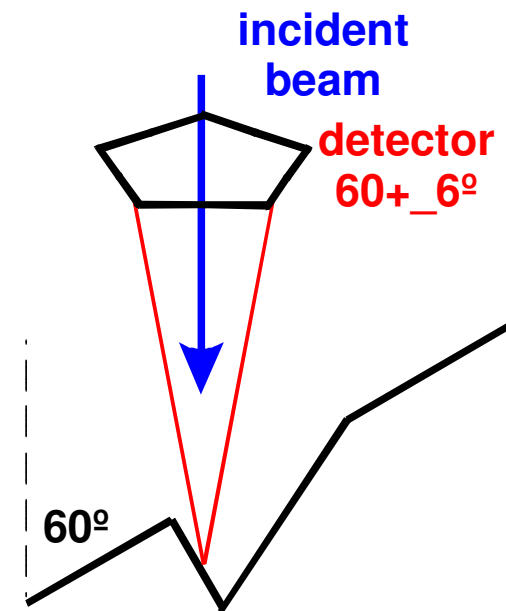
analyser on top

# Alternative configuration

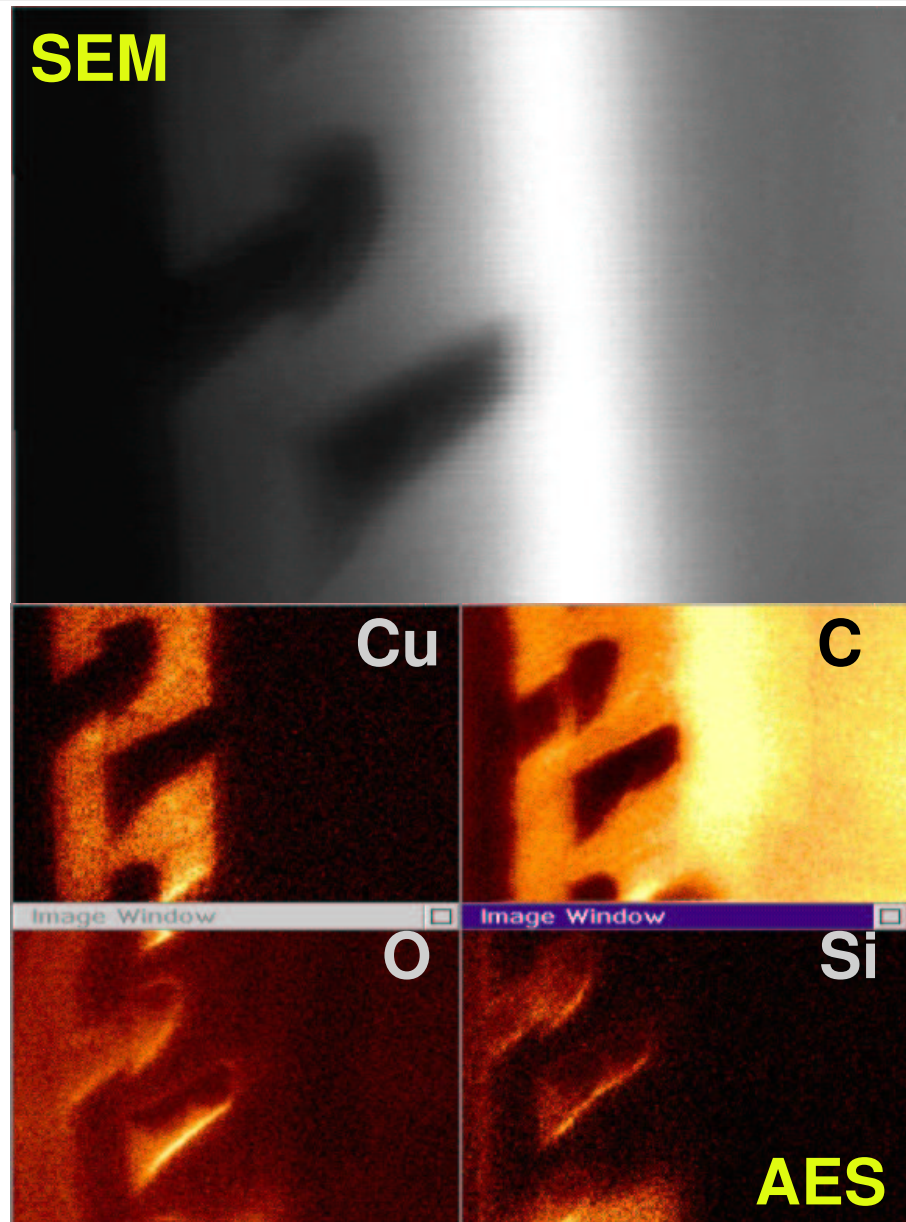
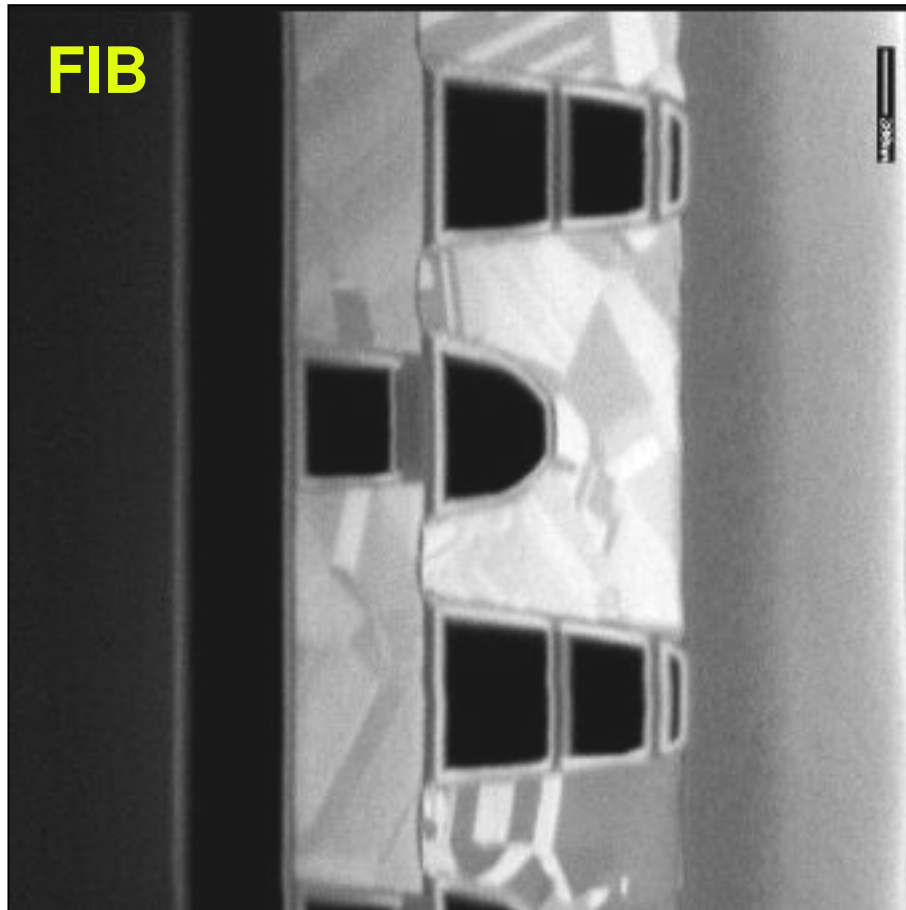
30° tilt : no detection



30° pre-tilt holder  
sample 90° rotated

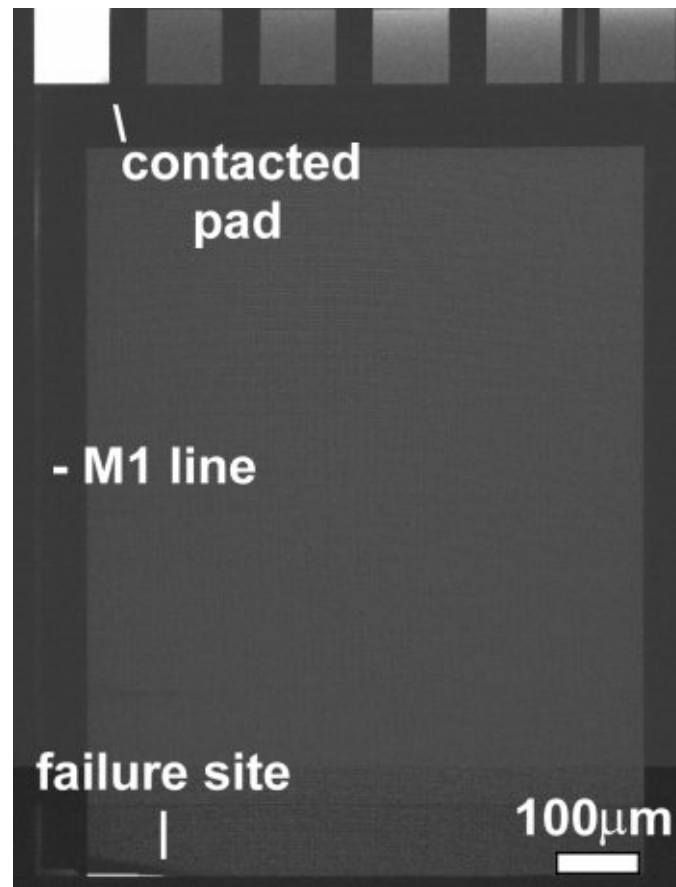


# FIB - AES Cu chains

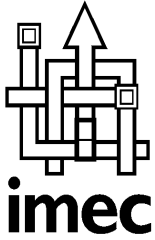


analyser on top

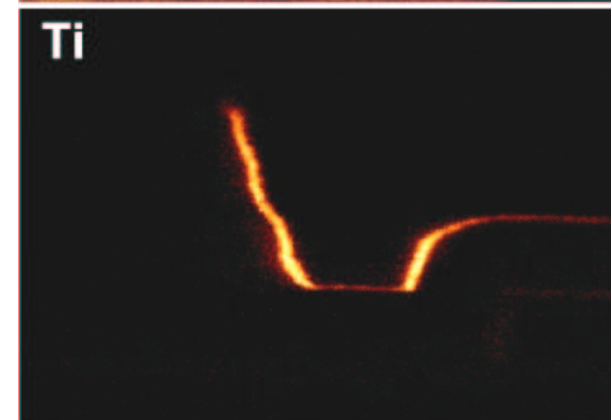
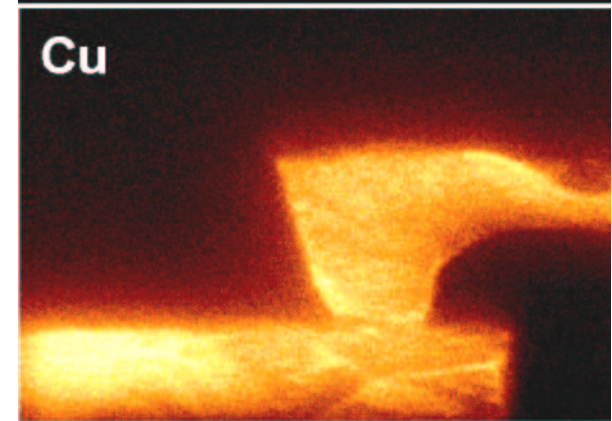
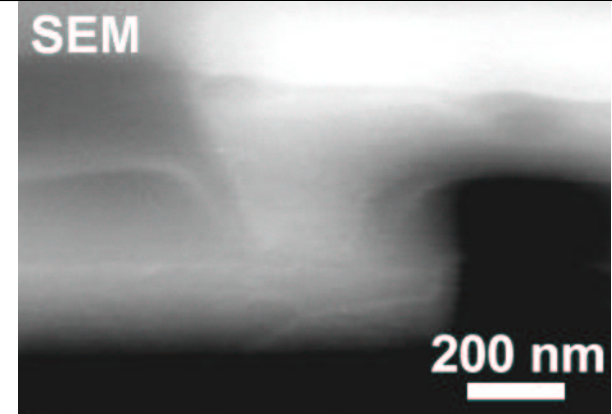
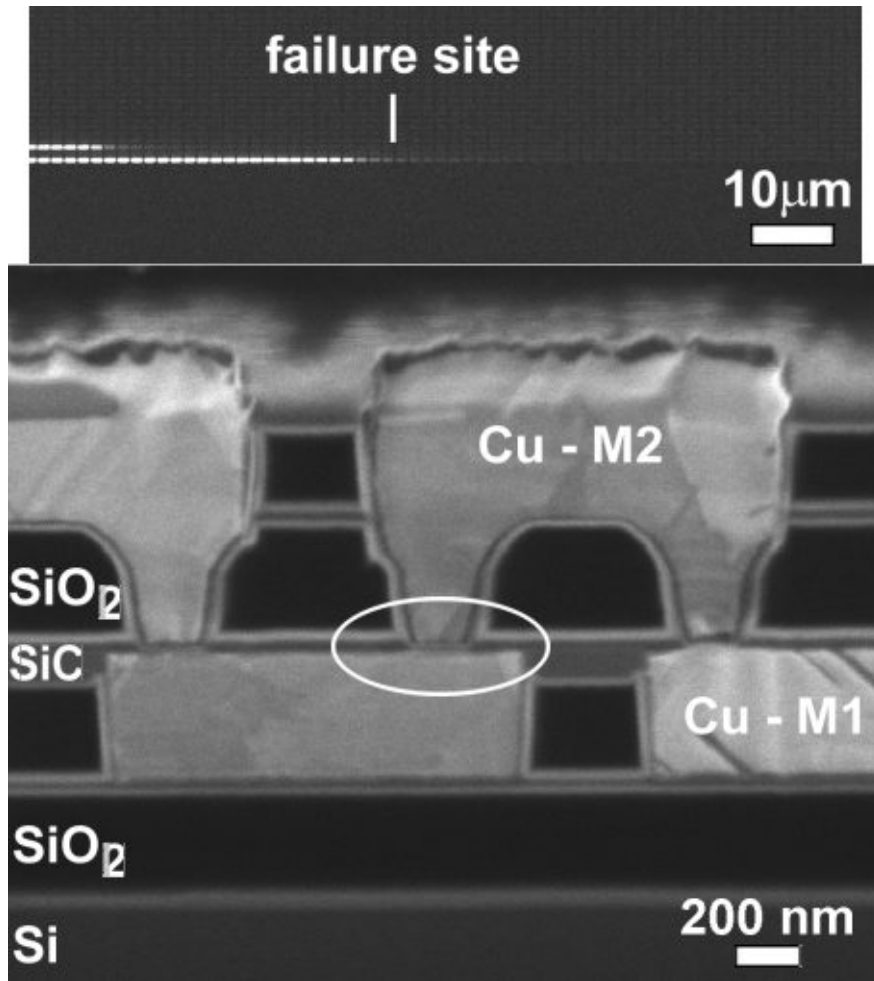
# Failure analysis Cu DD via chain

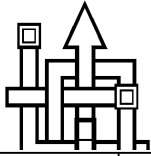


**voltage  
contrast**

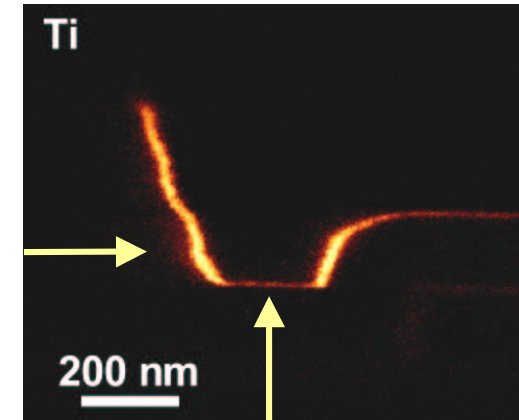
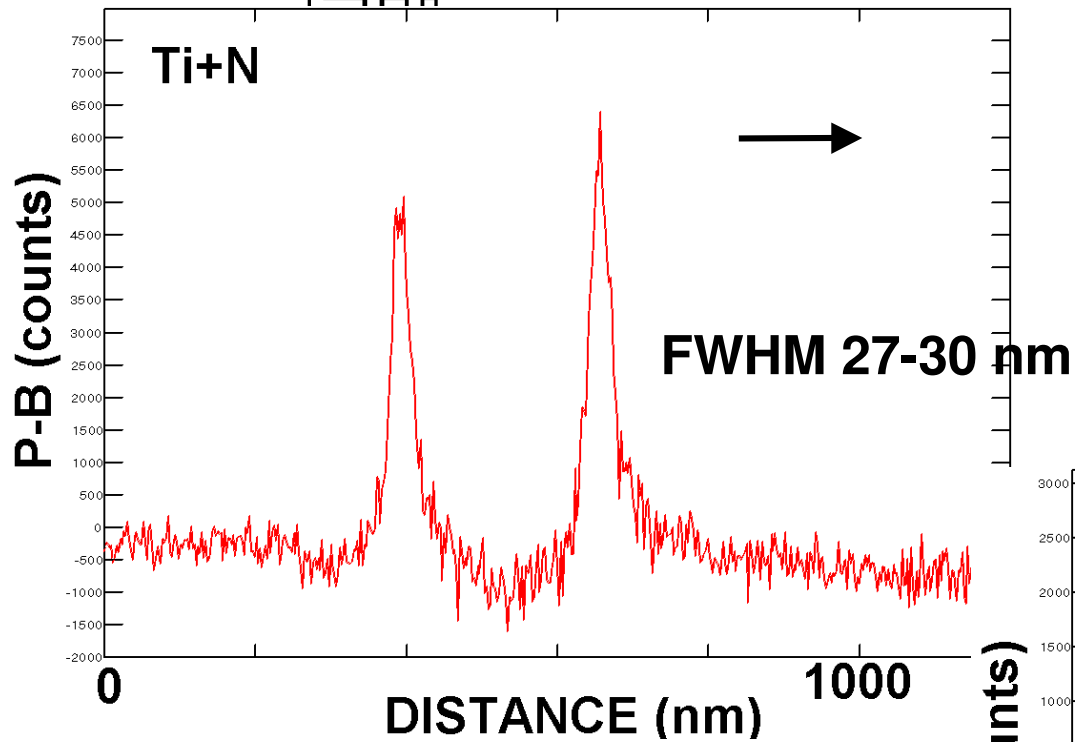


# Failure analysis Cu DD via chain

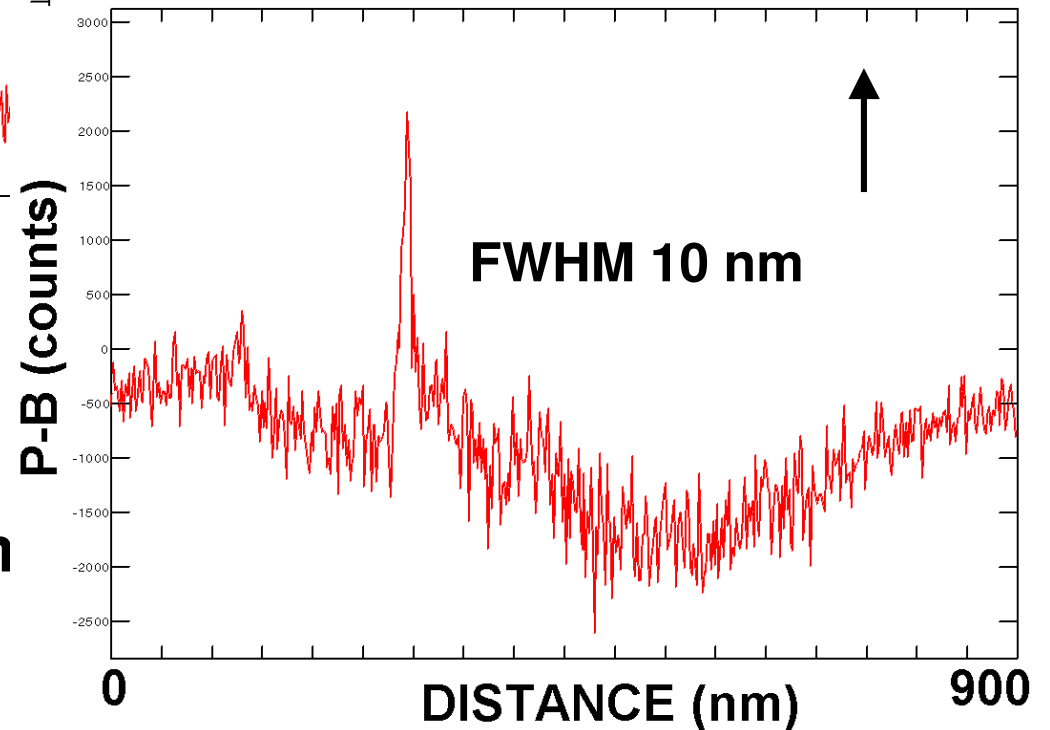


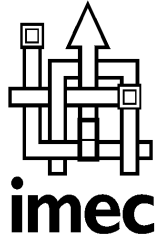


# Failure analysis Cu DD via chain



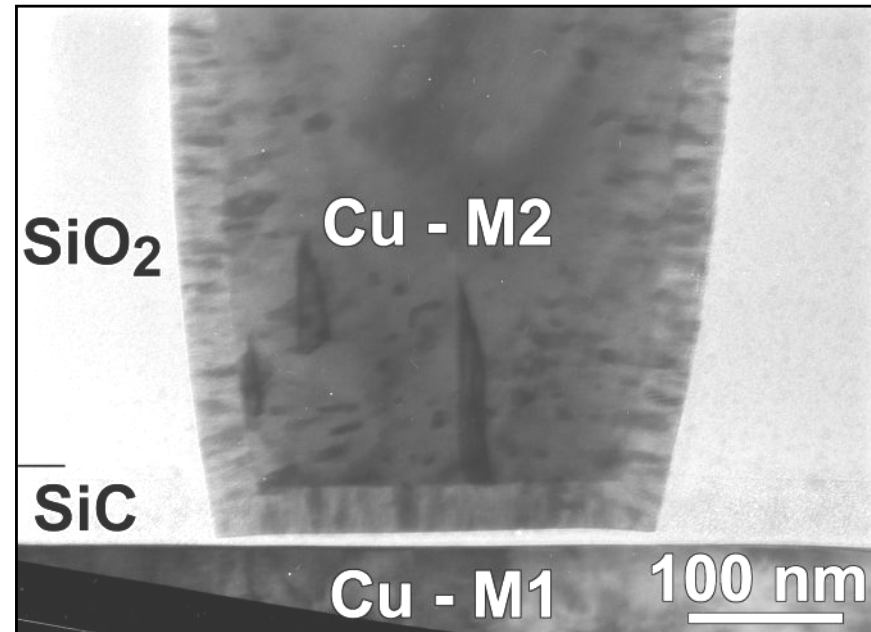
incidence angle  $75^\circ$   
i.e. width =  $10/\cos 75^\circ \sim 38$  nm





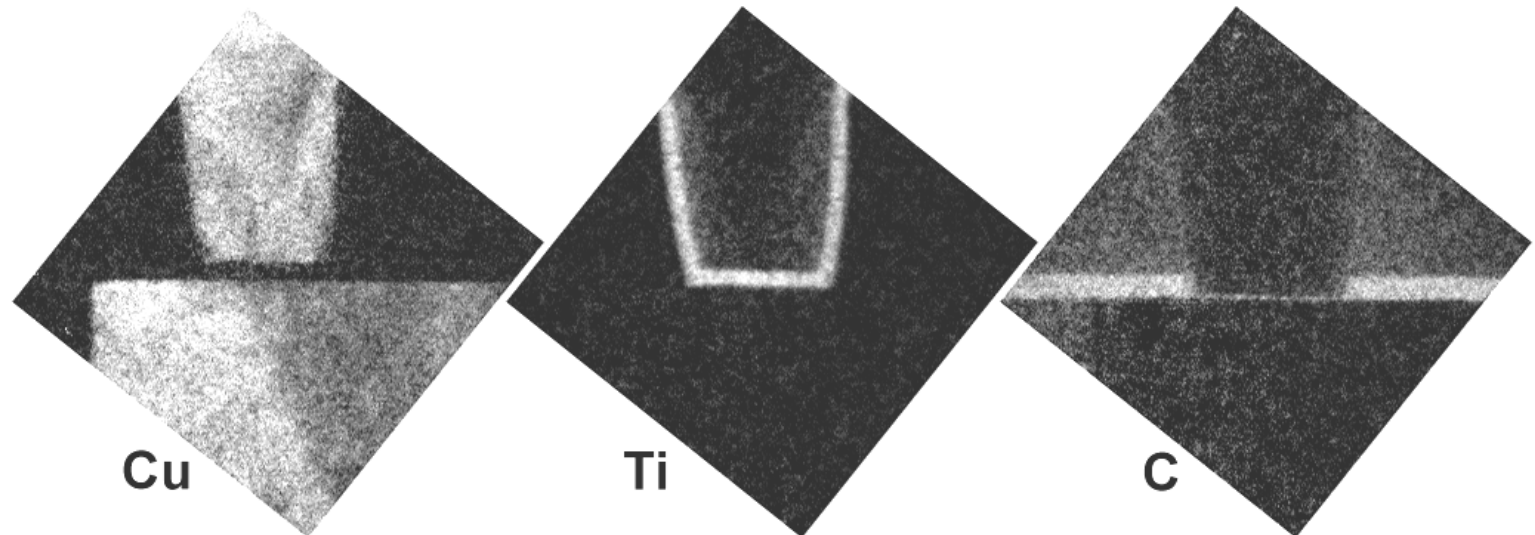
# Failure analysis Cu DD via chain

**TEM cross-section**



**barrier : ~ 25 nm**  
**SiC : 5-8 nm**

**EELS**



- **AES analysis standard FIB crater**
  - **15° configuration** : no detection deeper in the crater
  - **30° pre-tilt / 90° rotation** : detection on full crater wall, asymmetry effects
  - **drawbacks** : C/O contamination from air exposure : no sputter cleaning possible
  - **analysis 10 nm layers possible**
  - **thinner layers** : TEM required
- **AES on FIB cleaned edges (cleaving or polishing)** : avoids crater shape limitations, but not generally possible